

Panel Discussion



Global Semiconductor Alliance



**3D-ICs – Real or Imaginary:
And what would speed up adoption?**

Herb Reiter, eda2asic Consulting
Chair of GSA 3D TSV Programs
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- **Introduction**
- **Panelists' Positioning Statements**
 - **5 minutes each**
- **Q & A with the Audience**
- **Summary**



- **2D economical challenges:** NRE's, Risk, Time-to-Market,...
- **2D technical challenges:** Variability, leakage, noise,...

- **3D (and 2.5D) offer**
 - **Modularity → shorter TTM**
 - **Lower power**
 - **Higher bandwidth**
 - **Shorter latency**
 - **Smaller form-factor**
 - **Heterogeneous integration**
 - **Architectural flexibility**
 - **... lower cost**



- **Moderator: Herb Reiter, GSA & eda 2 asic Consulting**

- **Panelists:**
 - **Dusan Petranovic, Mentor Graphics**
 - **Technical Marketing Engineer**

 - **Bill Martin, E-System Design**
 - **Vice President**

 - **Rudy Hernandez, Texas Instruments**
 - **TSV SoC Readiness Program Manager**

 - **Rahul Deokar, Cadence Design Systems**
 - **Product Director**

